506907331 10/05/2021

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yun-Tse Chen	03/09/2021
Yan-Guei Chen	03/09/2021
Shi-Ming Lu	03/09/2021
Liang-Wei Huang	03/09/2021

RECEIVING PARTY DATA

Name:	Realtek Semiconductor Corp.	
Street Address:	2 Innovation Rd. II, Science Park	
City:	HsinChu	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17494797

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU

Address Line 1: 5F., NO.389, FUHE RD., YONGHE DIST.,

Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	REAP1168USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	10/05/2021

Total Attachments: 8

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PATENT REEL: 057709 FRAME: 0043

EPAS ID: PAT6954155



Title of Invention:

Parameter calibration method and semiconductor device utilizing the same

As the below named inventor, I hereby declare that: This declaration is directed to:				
The attached application, or	r			
☐ United States application numberfiled		_filed or)	or
☐ PCT international application	on number	filed	I on	
The above-identified application was	s made or authorized to be made	by me.		
I believe that I am the original inventapplication.	tor or an original joint inventor of	a claimed	invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	al false statement made in this de risonment of not more than five (eclaration 5) years, o	is punishable or both.	
In consideration of the payment by	Realtek Semiconductor C	orp.	having a postal add	ress of
2 Innovation Rd. II, Science P	Park, HsinChu 30076, Taiwa	an, R.O.0) .	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good at		.00), the re	eceipt of which is he	reby
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.				EE
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, said invention and said ecessary or desirable to carry out	Letters Pa	atent and said oses thereof.	
Note: An application data sheet (PTo inventive entity, must accompany thi				

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NPO#REA-P1168-USA:0 CUST#109A-271US

Docket No REAPI168USA

Inventor:	Yun-Tse Chen	Date	
			MAR 0.9 2021

LEGAL NAME OF INVENTOR(ASSIGNOR)

Signature: Yun-Tse Chen .

Page 2 of 8

Title of Invention:

Parameter calibration method and semiconductor device utilizing the same

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	ımber	filed on,		or
☐ PCT international applicatio	n number	filed	d on	
The above-identified application was	made or authorized to be mad	le by me.		
I believe that I am the original invent application.	or or an original joint inventor o	f a claimed	invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				
In consideration of the payment by	Realtek Semiconductor (Corp.	having a postal add	ress of
2 Innovation Rd. II, Science P	ark, HsinChu 30076, Taiw	an, R.O.	3.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ and valuable consideration.	1.00), the r	eceipt of which is he	reby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements tion and, in and to, all Letters F r any continuations, continuatio	which are atent to be n-in-part, d	disclosed in the e obtained for said iivisions, renewals,	EE
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbr n this assignment;	ance has t	een or will be made	or
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	olication, said invention and said ecessary or desirable to carry of	d Letters P ut the prop	atent and said oses thereof.	
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire nventive entity, must accompany this form. Use this form for each additional inventor.				

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NPO#REA-P1168-USA:0 CUST#109A-271US

Docket No REAP1168USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yan-Guei Chen Date: MAR 0 9 2021

Signature: Yan - Guer Chen

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NPO#REA-P1168-USA:0 CUST#109A-271US F#NPO-P0002E-US1201 DSB0-109U043322

Title of Invention:

Parameter calibration method and semiconductor device utilizing the same

As the below named inventor, I hereby declare that: This declaration is directed to:				
☑ The attached application, or				
☐ United States application number filed on, or				
☐ PCT international application numberfiled on				
The above-identified application was made or authorized to be made by me.				
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.				
I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.				
In consideration of the payment by Realtek Semiconductor Corp. having a postal addres	s of			
2 Innovation Rd. II, Science Park, HsinChu 30076, Taiwan, R.O.C.				
(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereb acknowledged, andfor other good and valuable consideration.	1			
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.				
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.				
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.				

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NPO#REA-P1168-USA:0 CUST#109A-271US

Docket No REAPI168USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Shi-Ming Lu

Date:

MAR 09 2021

Signature:

Shi-Ming Lu

Page 6 of 8

F#NPO-P0002E-US1201 DSB0-109U043322

NPO#REA-P1168-USA:0 CUST#109A-271US

Title of Invention:

Parameter calibration method and semiconductor device utilizing the same

As the below named inventor, I hereb This declaration is directed to:	y declare that:			
The attached application, or				
☐ United States application number		filed on	or	
☐ PCT international application	filed on			
The above-identified application was	made or authorized to be made	by me.		
I believe that I am the original invento application.	r or an original joint inventor of a	claimed invention in the		
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impris				
In consideration of the payment by	Realtek Semiconductor Co	prp. having a postal add	ress of	
2 Innovation Rd. II, Science Pa	rk, HsinChu 30076, Taiwar	n, R.O.C.		
(referred to as "ASSIGNEE" below) to acknowledged, andfor other good and	l of the sum of One Dollar (\$ 1.0 I valuable consideration.	00), the receipt of which is he	reby	
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, and	d to any and all improvements w on and, in and to, all Letters Pat any continuations, continuation-i	hich are disclosed in the ent to be obtained for said in-part, divisions, renewals,	EE	
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.				
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for <u>each additional inventor.</u>				

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NPO#REA-P1168-USA:0 CUST#109A-271US

Docket No REAPI168USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Liang-Wei Huang Date: MAR 0 9 2021

Signature: Liang-Wei Huang

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F#NPO-P0002E-US1201 DSB0-109U043322

NPO#REA-P1168-USA:0 CUST#109A-271US

RECORDED: 10/05/2021